

RoHS Compliant Product
A suffix of "-C" specifies halogen & lead-free

DESCRIPTION

The SSPRD6560-C is the highest performance trench N-Ch and P-Ch MOSFETs with extreme high cell density, which provide excellent $R_{DS(ON)}$ and gate charge for most of the synchronous buck converter applications.

The SSPRD6560-C meet the RoHS and Green Product requirement with full function reliability approved.

FEATURES

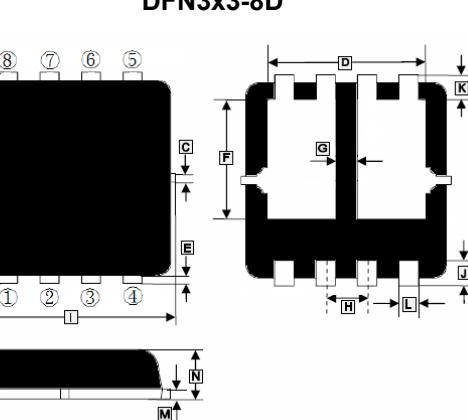
- Advanced High Cell Density Trench Technology
- Super Low Gate Charge
- Green Device Available

MARKING



PACKAGE INFORMATION

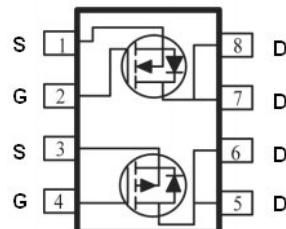
Package	MPQ	Leader Size
DFN3x3-8D	3K	13 inch



REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	3	3.2	H	0.65	BSC
B	3.25	3.45	I	3.2	3.4
C	0.13	BSC	J	0.3	0.5
D	2.39	2.59	K	0.3	0.5
E	0.13	BSC	L	0.25	0.35
F	1.78	1.98	M	0.1	0.25
G	0.3	BSC	N	0.7	0.8

ORDER INFORMATION

Part Number	Type
SSPRD6560-C	Lead (Pb)-free and Halogen-free



ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Ratings		Unit	
		N-Ch	P-Ch		
Drain-Source Voltage	V_{DS}	60	-60	V	
Gate-Source Voltage	V_{GS}	± 20		V	
Continuous Drain Current, @ $V_{GS}=10V^1$	$T_C=25^\circ C$	I_D	6.8	A	
	$T_C=100^\circ C$		4.2		
	$T_A=25^\circ C$		4.3		
	$T_A=70^\circ C$		2.8		
Pulsed Drain Current ³	I_{DM}	20	-20	A	
Total Power Dissipation	$T_C=25^\circ C$	P_D	3.78	W	
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55~150		°C	
Thermal Data					
Thermal Resistance Junction-Ambient ¹	$R_{\theta JA}$	84		°C/W	
Thermal Resistance Junction-Ambient ²		135			
Thermal Resistance Junction-Case ¹		$R_{\theta JC}$	33		

N-CHANNEL ELECTRICAL CHARACTERISTICS ($T_J=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Drain-Source Breakdown Voltage	BV_{DSS}	60	-	-	V	$V_{GS}=0$, $I_D=250\mu\text{A}$
Gate Threshold Voltage	$V_{GS(\text{th})}$	1	-	2.5	V	$V_{DS}=V_{GS}$, $I_D=250\mu\text{A}$
Forward Transfer Conductance	g_{fs}	-	25.3	-	S	$V_{DS}=5\text{V}$, $I_D=4.3\text{A}$
Gate-Source Leakage Current	I_{GSS}	-	-	± 100	nA	$V_{GS} = \pm 20\text{V}$
Drain-Source Leakage Current	I_{DSS}	-	-	1	μA	$V_{DS}=48\text{V}$, $V_{GS}=0$
		-	-	5		
Static Drain-Source On-Resistance ⁴	$R_{DS(\text{ON})}$	-	-	45	$\text{m}\Omega$	$V_{GS}=10\text{V}$, $I_D=4.3\text{A}$
		-	-	55		$V_{GS}=4.5\text{V}$, $I_D=4\text{A}$
Total Gate Charge	Q_g	-	19	-	nC	$I_D=4.3\text{A}$ $V_{DS}=48\text{V}$ $V_{GS}=10\text{V}$
Gate-Source Charge	Q_{gs}	-	2.5	-		
Gate-Drain ("Miller") Change	Q_{gd}	-	5	-		
Turn-on Delay Time	$T_{d(\text{on})}$	-	2.8	-	nS	$V_{DS}=30\text{V}$ $I_D=1\text{A}$ $V_{GS}=10\text{V}$ $R_G=3.3\Omega$
Rise Time	T_r	-	16.6	-		
Turn-off Delay Time	$T_{d(\text{off})}$	-	21.2	-		
Fall Time	T_f	-	5.6	-		
Input Capacitance	C_{iss}	-	1027	-	pF	$V_{GS}=0$ $V_{DS}=15\text{V}$ $f=1\text{MHz}$
Output Capacitance	C_{oss}	-	65	-		
Reverse Transfer Capacitance	C_{rss}	-	46	-		
Source-Drain Diode						
Continuous Source Current ¹	I_s	-	-	4.3	A	
Pulsed Source Current ³	I_{SM}	-	-	20		
Forward on Voltage ⁴	V_{SD}	-	-	1.2	V	$V_{GS}=0$, $I_s=1\text{A}$, $T_J=25^\circ\text{C}$

P-CHANNEL ELECTRICAL CHARACTERISTICS ($T_J=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Drain-Source Breakdown Voltage	BV_{DSS}	-60	-	-	V	$\text{V}_{\text{GS}}=0$, $\text{I}_D = -250\mu\text{A}$
Gate Threshold Voltage	$\text{V}_{\text{GS}(\text{th})}$	-1	-	-2.5	V	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}$, $\text{I}_D = -250\mu\text{A}$
Forward Transfer Conductance	g_{fs}	-	8.7	-	S	$\text{V}_{\text{DS}}= -5\text{V}$, $\text{I}_D = -3.2\text{A}$
Gate-Source Leakage Current	I_{GSS}	-	-	± 100	nA	$\text{V}_{\text{GS}}= \pm 20\text{V}$
Drain-Source Leakage Current	I_{DSS}	-	-	-1	μA	$\text{V}_{\text{DS}}= -48\text{V}$, $\text{V}_{\text{GS}}=0$
$T_J=25^\circ\text{C}$		-	-	-5		
Static Drain-Source On-Resistance ⁴	$\text{R}_{\text{DS}(\text{ON})}$	-	-	82	$\text{m}\Omega$	$\text{V}_{\text{GS}}= -10\text{V}$, $\text{I}_D = -3.2\text{A}$
		-	-	102		$\text{V}_{\text{GS}}= -4.5\text{V}$, $\text{I}_D = -3\text{A}$
Total Gate Charge	Q_g	-	11.8	-	nC	$\text{I}_D = -3.2\text{A}$ $\text{V}_{\text{DS}}= -20\text{V}$ $\text{V}_{\text{GS}}= -4.5\text{V}$
Gate-Source Charge	Q_{gs}	-	1.9	-		
Gate-Drain ("Miller") Change	Q_{gd}	-	6.5	-		
Turn-on Delay Time	$\text{T}_{\text{d}(\text{on})}$	-	8.8	-		
Rise Time	T_r	-	19.6	-	nS	$\text{V}_{\text{DS}}= -15\text{V}$ $\text{I}_D = -1\text{A}$ $\text{V}_{\text{GS}}= -10\text{V}$ $\text{R}_G=3.3\Omega$
Turn-off Delay Time	$\text{T}_{\text{d}(\text{off})}$	-	47.2	-		
Fall Time	T_f	-	9.6	-		
Input Capacitance	C_{iss}	-	1080	-	pF	$\text{V}_{\text{GS}}=0$ $\text{V}_{\text{DS}}= -15\text{V}$ $f=1\text{MHz}$
Output Capacitance	C_{oss}	-	97	-		
Reverse Transfer Capacitance	C_{rss}	-	50	-		
Source-Drain Diode						
Continuous Source Current ¹	I_s	-	-	-3.2	A	
Pulsed Source Current ³	I_{SM}	-	-	-20		
Forward on Voltage ⁴	V_{SD}	-	-	-1.2	V	$\text{V}_{\text{GS}}=0$, $\text{I}_s = -1\text{A}$, $T_J=25^\circ\text{C}$

Notes:

1. Surface mounted on a 1 inch² FR-4 board with 2OZ copper.
2. When mounted on Min. copper pad.
3. Pulse width limited by maximum junction temperature, pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
4. Pulse Test: pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.

N-CHANNEL CHARACTERISTIC CURVE

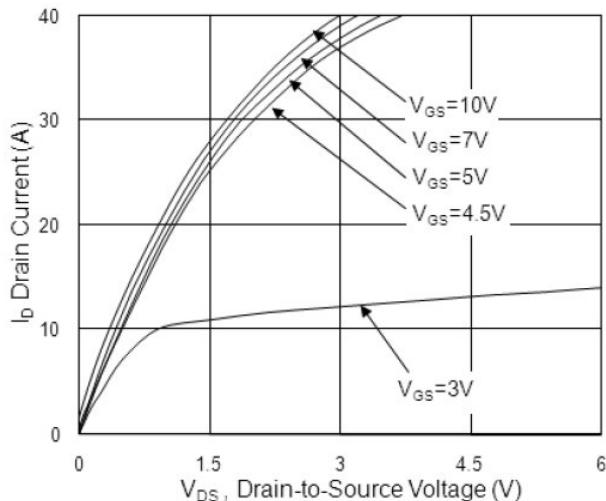


Fig.1 Typical Output Characteristics

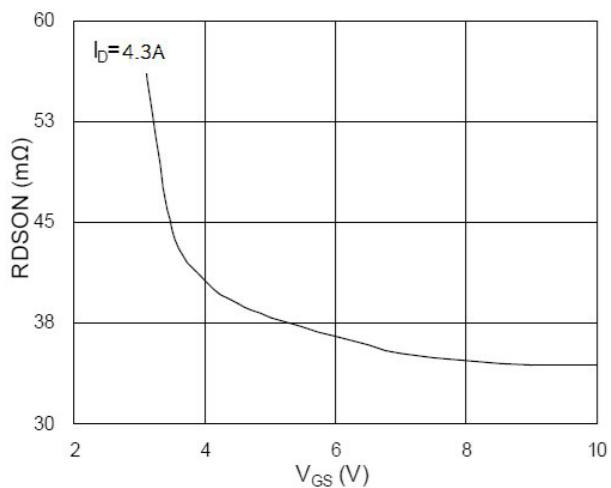


Fig.2 On-Resistance vs. Gate-Source

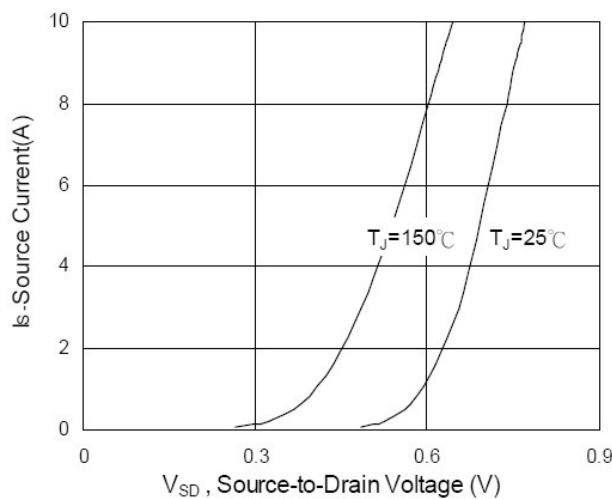


Fig.3 Forward Characteristics Of Reverse

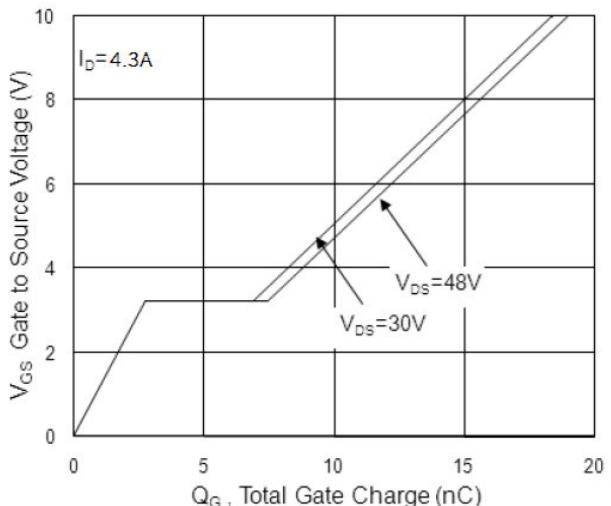


Fig.4 Gate-Charge Characteristics

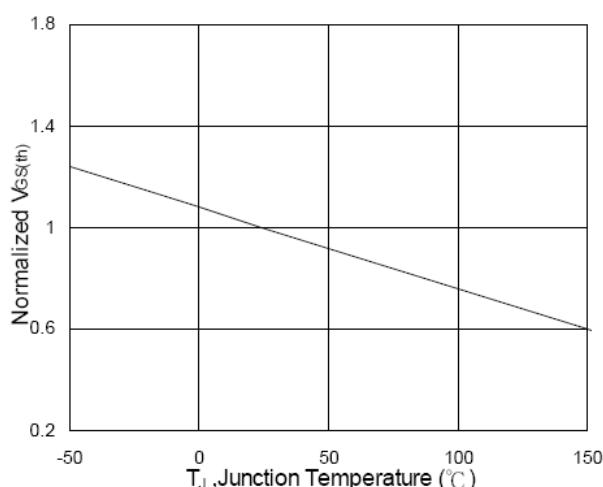


Fig.5 Normalized V_{GS(th)} vs. T_J

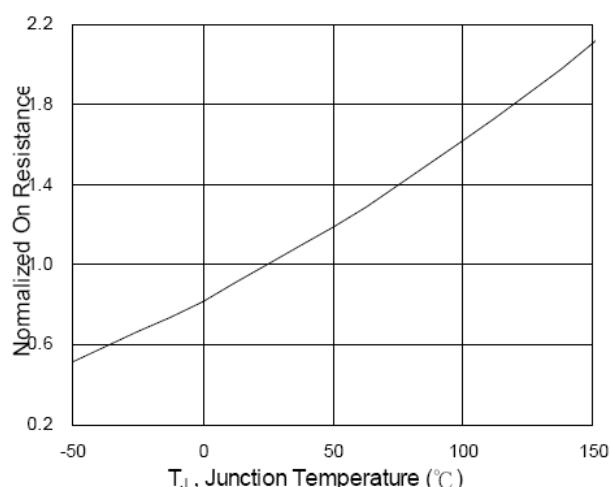


Fig.6 Normalized R_D_(ON) vs. T_J

N-CHANNEL CHARACTERISTIC CURVE

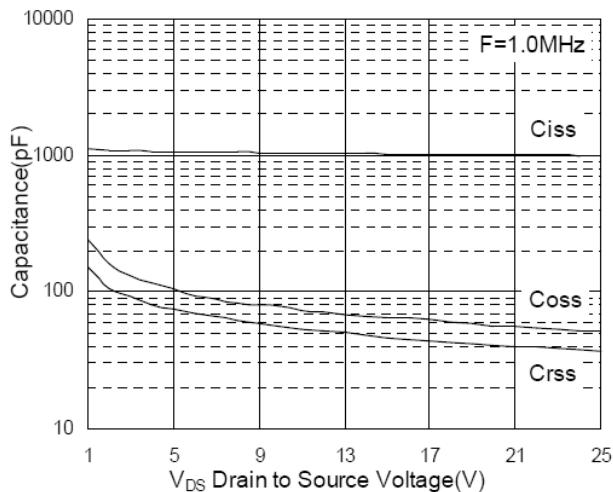


Fig.7 Capacitance

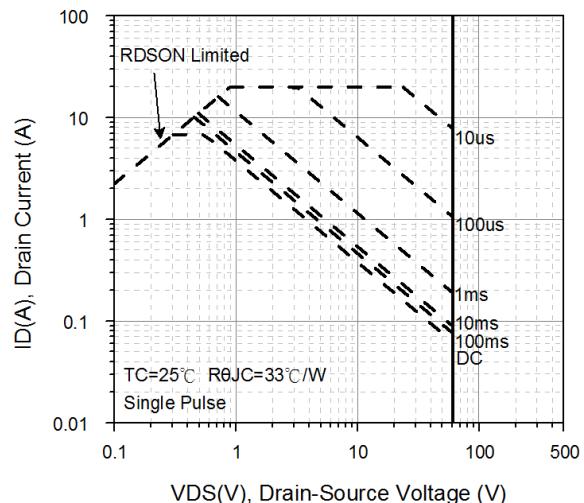


Fig.8 Safe Operating Area

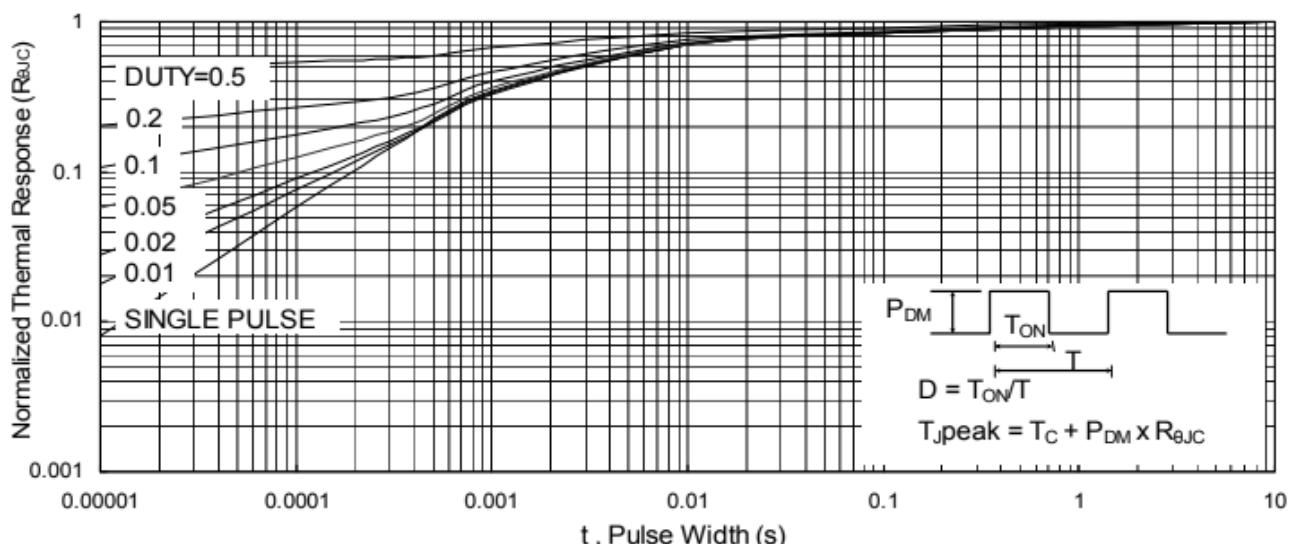


Fig.9 Normalized Maximum Transient Thermal Impedance

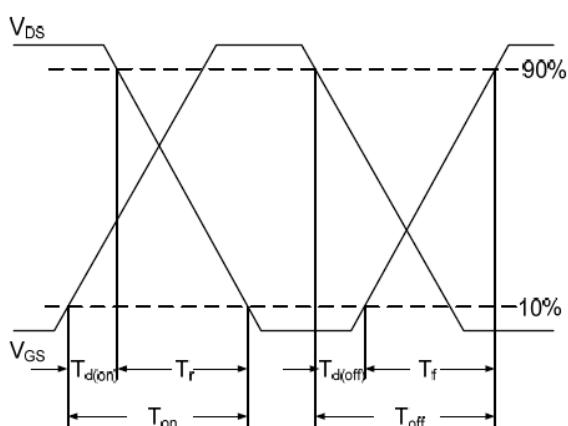


Fig.10 Switching Time Waveform

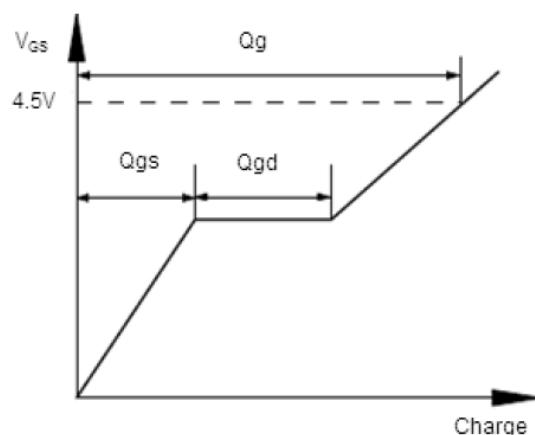


Fig.11 Gate Charge Waveform

P-CHANNEL CHARACTERISTIC CURVE

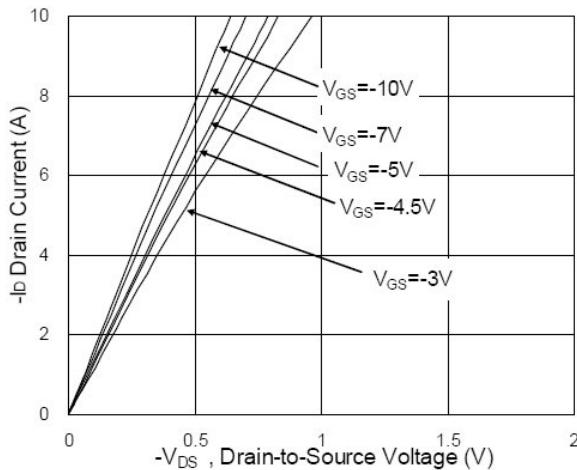


Fig.1 Typical Output Characteristics

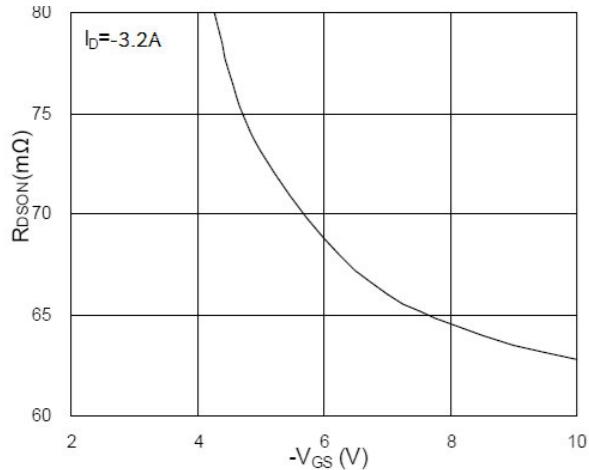


Fig.2 On-Resistance v.s Gate-Source

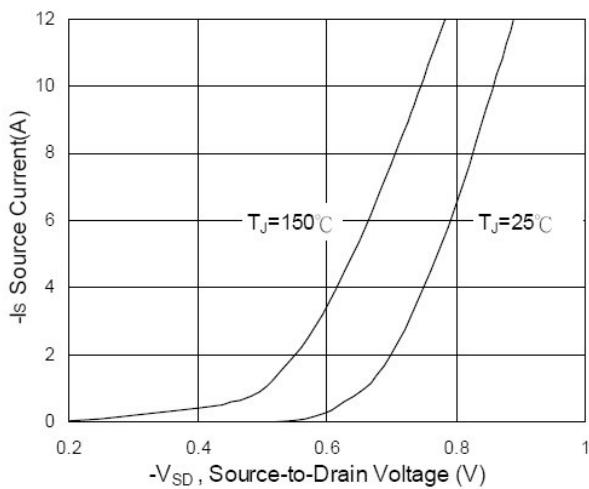


Fig.3 Forward Characteristics of Reverse

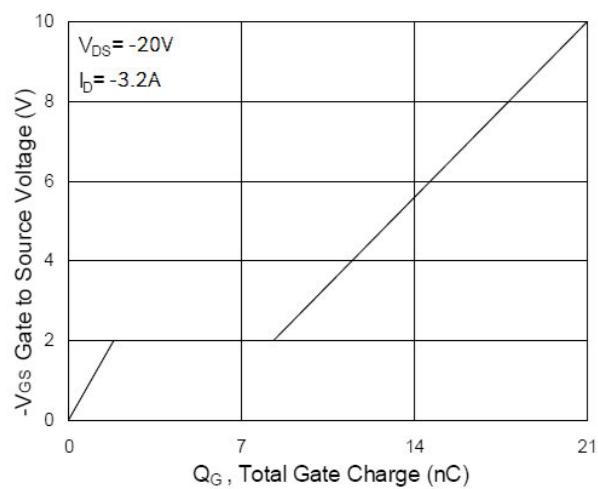


Fig.4 Gate-Charge Characteristics

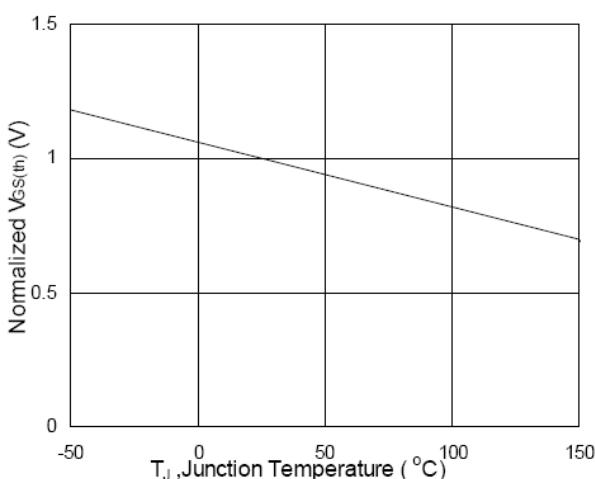


Fig.5 Normalized $V_{GS(th)}$ v.s T_J

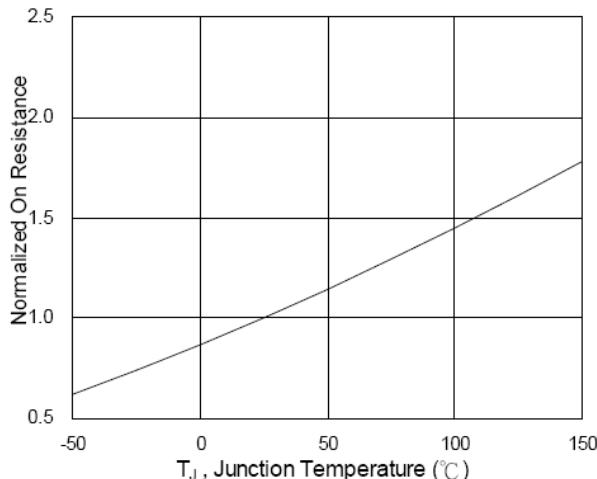


Fig.6 Normalized $R_{DS(ON)}$ v.s T_J

P-CHANNEL CHARACTERISTIC CURVE

